Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	271	(@ad<"20020506") and (cap near wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 17:00
L2	90	L1 and (mold or molding or plate or diceor press)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 16:58
L3	110	L1 and (mold or molding or plate or dice or press)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 17:01
L4	1272	(@ad<"20020506") and ((lod or cover or sink or spreader) near wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 17:02
L5	501	L4 and (mold or molding or plate or dice or press)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 17:01
L6	58617	((mold or molding or plate or dice or press) with (semiconducor or silicon))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 17:01
L7	136	L6 and (@ad<"20020506") and ((cap or lid or cover or sink or spreader) near wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/15 17:02